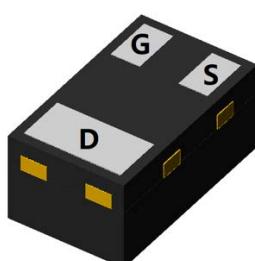


P-Channel Enhancement Mode Field Effect Transistor

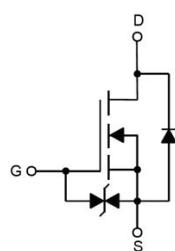


Top View



Bottom View

DFN1006-3L



Product Summary

- V_{DS} -20V
- I_D -0.65A
- $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) <850 mohm
- $R_{DS(ON)}$ (at $V_{GS}=-2.5V$) <1200 mohm
- $R_{DS(ON)}$ (at $V_{GS}=-1.8V$) <2000 mohm
- ESD Protected Up to 2.0KV (HBM)

General Description

- Trench Power LV MOSFET technology
- High Density Cell Design for Low $R_{DS(ON)}$
- High Speed switching
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Interfacing, Logic switch
- Load switch
- Power management

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Maximum	Unit
Drain-source Voltage		V_{DS}	-20	V
Gate-source Voltage		V_{GS}	± 12	V
Drain Current	$T_A=25^\circ\text{C}$ Steady State	I_D	-0.65	A
	$T_A=70^\circ\text{C}$ Steady State		-0.52	
Pulsed Drain Current ^A		I_{DM}	-2.0	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$ Steady State		P_D	0.9	W
Thermal Resistance Junction-to-Ambient @ Steady State ^B		R_{QJA}	138	$^\circ\text{C} / \text{W}$
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^\circ\text{C}$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCA3139KB	F1	9A	10000	100000	400000	7" reel

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}, T_c=25^\circ\text{C}$			-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 10\text{V}, V_{\text{DS}}=0\text{V}$		± 1.5	± 10	μA
		$V_{\text{GS}}= \pm 8\text{V}, V_{\text{DS}}=0\text{V}$		± 500	± 2000	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-0.35	-0.62	-1.2	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}= -4.5\text{V}, I_{\text{D}}=-0.5\text{A}$		580	850	mΩ
		$V_{\text{GS}}= -2.5\text{V}, I_{\text{D}}=-0.3\text{A}$		855	1200	
		$V_{\text{GS}}= -1.8\text{V}, I_{\text{D}}=-0.2\text{A}$		1350	2000	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=-0.65\text{A}, V_{\text{GS}}=0\text{V}$		-0.8	-1.2	V
Maximum Body-Diode Continuous Current	I_{S}				-0.65	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-10\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		71		pF
Output Capacitance	C_{oss}			20		
Reverse Transfer Capacitance	C_{rss}			15		
Gate resistance	R_g	f=1MHz, Open Drain		85		Ω
Switching Parameters						
Total Gate Charge	Q_g	$V_{\text{GS}}=-4.5\text{V}, V_{\text{DD}}=-10\text{V}, I_{\text{D}}=-0.5\text{A}$		1.24		nC
Gate Source Charge	Q_{gs}			0.37		
Gate Drain Charge	Q_{gd}			0.27		
Reverse Recovery Charge	Q_{rr}	$I_F=-0.5\text{A}, di/dt=-20\text{A/us}$		0.97		ns
Reverse Recovery Time	t_{rr}			26		
Turn-on Delay Time	$t_{\text{D(on)}}$			4		
Turn-on Rise Time	t_r	$V_{\text{GS}}=-4.5\text{V}, V_{\text{DD}}=-10\text{V}, R_L=2.5\Omega, R_{\text{GEN}}=3\Omega$		19		
Turn-off Delay Time	$t_{\text{D(off)}}$			16		
Turn-off Fall Time	t_f			25		

- A. Pulse Test: Pulse Width $\leq 300\text{us}$, Duty cycle $\leq 2\%$.
- B. The value of R_{GJA} is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The Power dissipation P_D is based on R_{GJA} and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design, and the maximum temperature of 150°C may be used if the PCB allows it to.

■ Typical Performance Characteristics

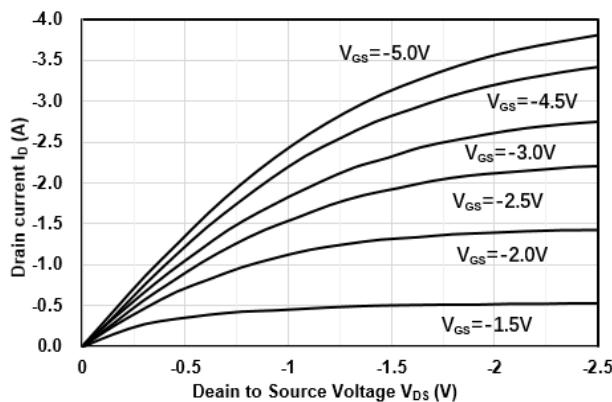


Figure1. Output Characteristics

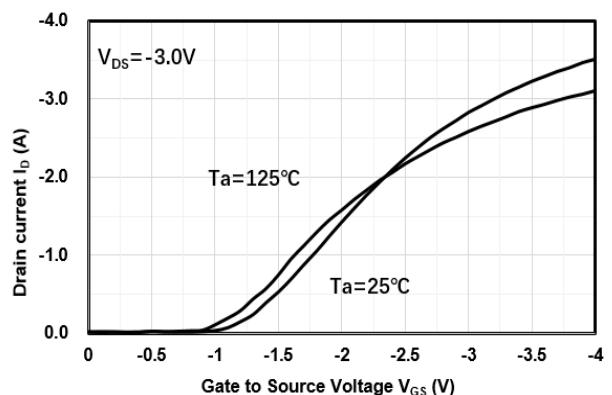


Figure2. Transfer Characteristics

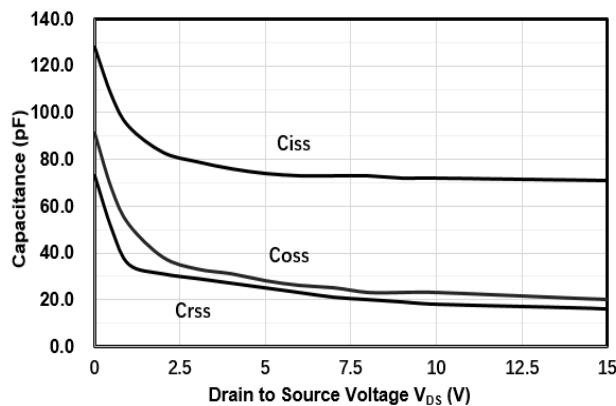


Figure3. Capacitance Characteristics

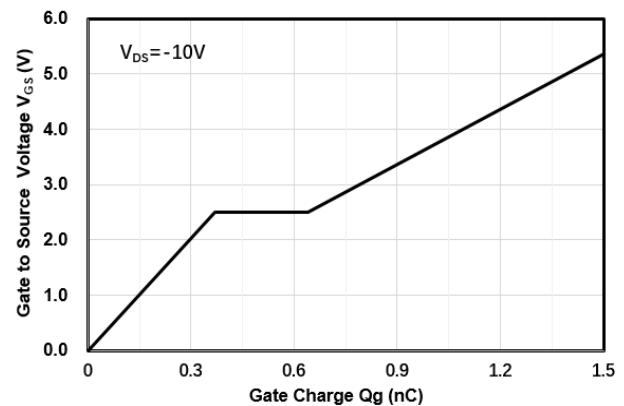


Figure4. Gate Charge

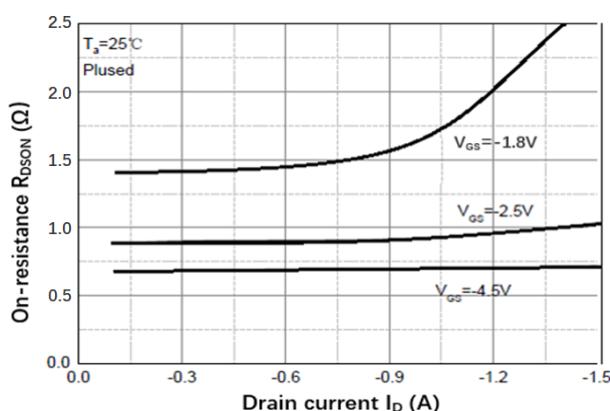


Figure5. Drain-Source on Resistance

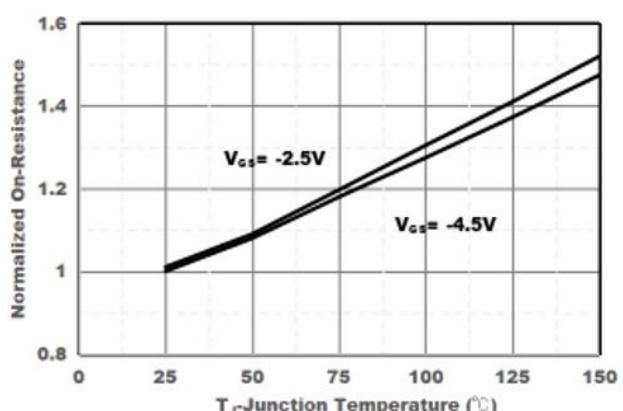


Figure6. Drain-Source on Resistance

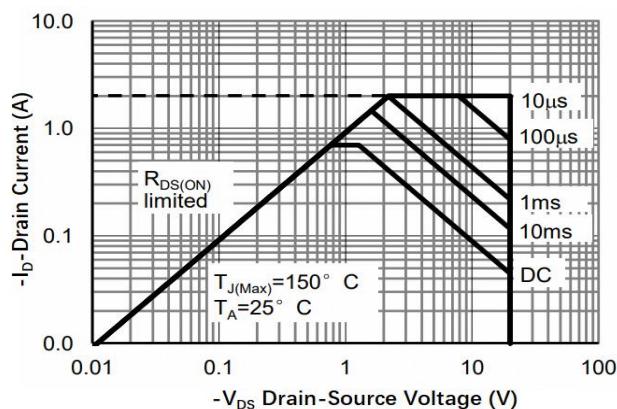


Figure7. Safe Operation Area

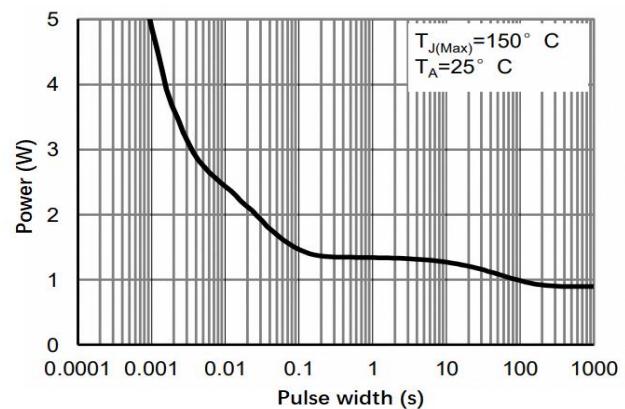


Figure8. Pulse Power Rating Junction-to Ambient

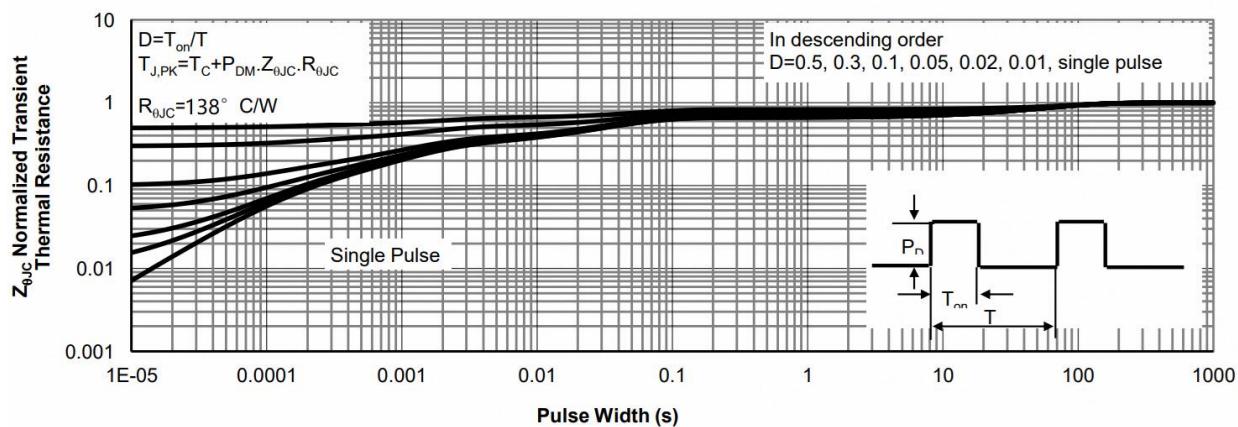
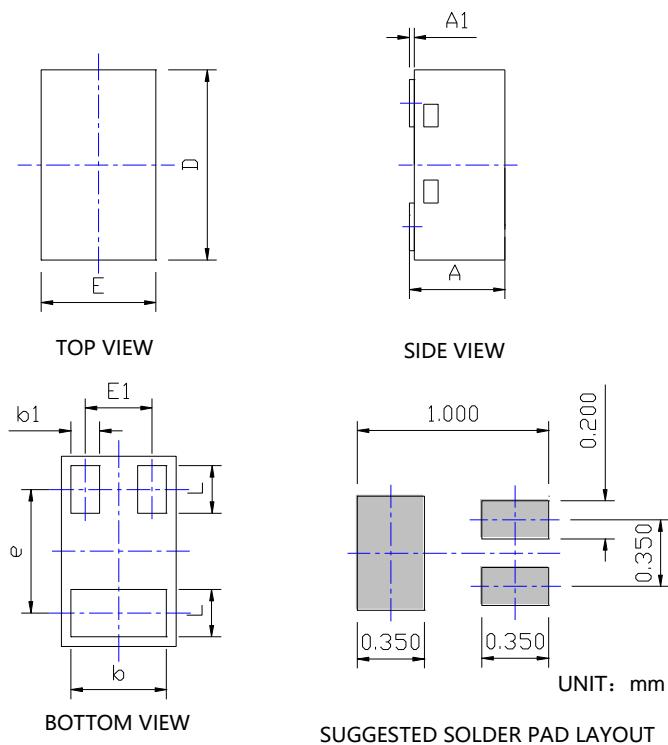


Figure9. Normalized Maximum Transient Thermal Impedance

■ DFN1006-3L Package information



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	0.42	---	0.55
A1	0.025REF		
b	0.45	0.50	0.55
b1	0.10	0.15	0.20
D	0.95	1.00	1.05
E	0.55	0.60	0.65
E1	0.35BSC		
e	0.65BSC		
L	0.20	0.25	0.30

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE LEAD BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

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